

## FEATURES

- ESD Protection for RS-232 Bus Pins
  - $\pm 15$ -kV Human-Body Model (HBM)
  - $\pm 8$ -kV IEC61000-4-2, Contact Discharge
  - $\pm 15$ -kV IEC61000-4-2, Air-Gap Discharge
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V  $V_{CC}$  Supply
- Operates up to 500 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 1  $\mu$ A Typ
- External Capacitors . . .  $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s) for SNx5C3223E

## APPLICATIONS

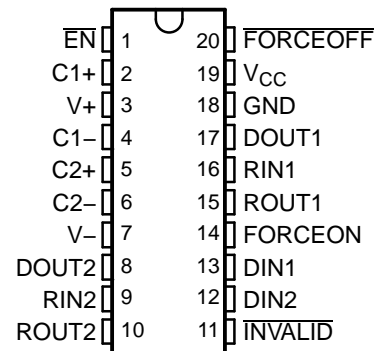
- Battery-Powered Systems
- PDAs
- Notebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment

## DESCRIPTION/ORDERING INFORMATION

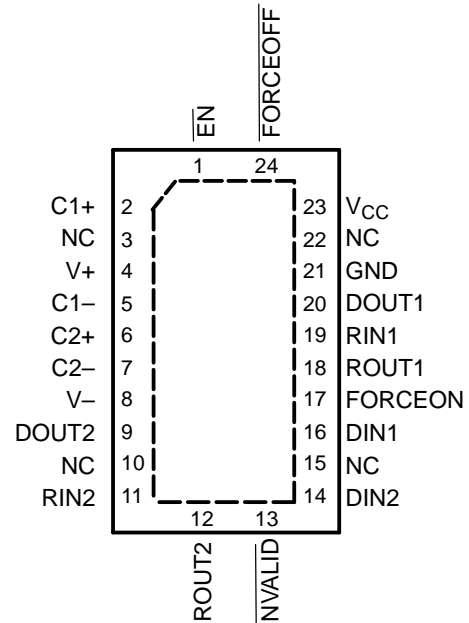
The MAX3223E consists of two line drivers, two line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The device operates at typical data signaling rates up to 500 kbit/s and a maximum of 30-V/ $\mu$ s driver output slew rate.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and EN is high, both drivers and receivers are shut off, and the supply current is reduced to 1 mA. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than  $-2.7$  V, or has been between  $-0.3$  V and 0.3 V for less than 30  $\mu$ s. INVALID is low (invalid data) if the receiver input voltage is between  $-0.3$  V and 0.3 V for more than 30  $\mu$ s. Refer to Figure 4 for receiver input levels.

DB, DW, OR PW PACKAGE  
(TOP VIEW)



RHL PACKAGE  
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**MAX3223E**  
**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER**  
**WITH ±15-kV ESD PROTECTION**



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**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–0°C to 70°C	SOIC – DW	Tube of 25	MAX3223ECDW	MAX3223EC
		Reel of 2000	MAX3223ECDWR	
	SSOP – DB	Tube of 70	MAX3223ECDB	MP223EC
		Reel of 2000	MAX3223ECDBR	
	TSSOP – PW	Tube of 70	MAX3223ECPW	MP223EC
		Reel of 2000	MAX3223ECPWR	
–40°C to 85°C	SOIC – DW	Tube of 25	MAX3223EIDW	MAX3223EI
		Reel of 2000	MAX3223EIDWR	
	SSOP – DB	Tube of 70	MAX3223EIDB	MP223EI
		Reel of 2000	MAX3223EIDBR	
	TSSOP – PW	Tube of 70	MAX3223EIPW	MP223EI
		Reel of 2000	MAX3223EIPWR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

**FUNCTION TABLES**

**EACH DRIVER<sup>(1)</sup>**

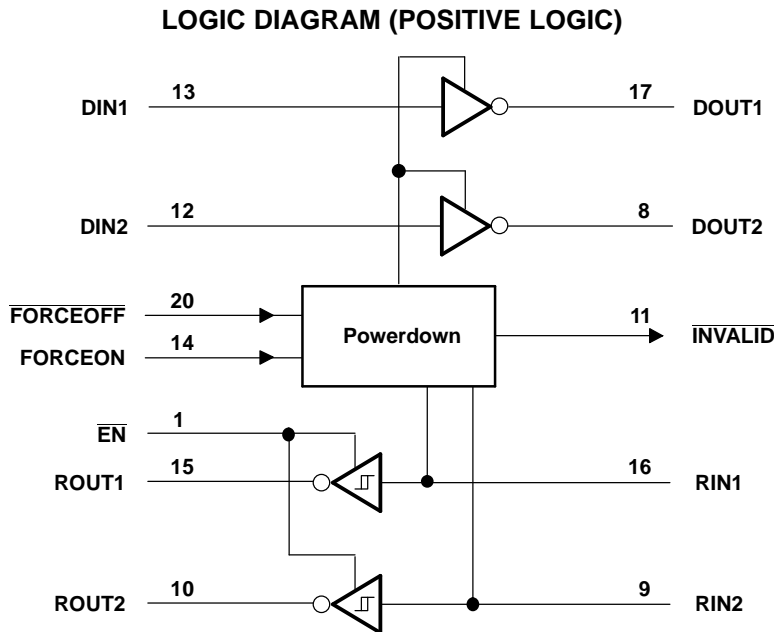
INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

**EACH RECEIVER<sup>(1)</sup>**

INPUTS			OUTPUT DOUT
RIN	EN	VALID RIN RS-232 LEVEL	
L	L	X	H
H	L	X	L
X	H	X	Z
Open	L	No	H

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



Pin numbers are for the DB, DW, and PW packages.

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.3	6	V
$V+$	Positive-output supply voltage range <sup>(2)</sup>	-0.3	7	V
$V-$	Negative-output supply voltage range <sup>(2)</sup>	0.3	-7	V
$V+ - V-$	Supply voltage difference <sup>(2)</sup>		13	V
$V_I$	Input voltage range	Driver (FORCEOFF, FORCEON, $\overline{EN}$ )		V
		Receiver		
$V_O$	Output voltage range	Driver		V
		Receiver ( $\overline{INVALID}$ )		
$\theta_{JA}$	Package thermal impedance <sup>(3)(4)</sup>	DB package		°C/W
		DW package		
		PW package		
		RHL package		
$T_J$	Operating virtual junction temperature		150	°C
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

# MAX3223E

## 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

### WITH $\pm 15$ -kV ESD PROTECTION

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### Recommended Operating Conditions<sup>(1)</sup>

See Figure 6

				MIN	NOM	MAX	UNIT
Supply voltage		V <sub>CC</sub> = 3.3 V		3	3.3	3.6	V
		V <sub>CC</sub> = 5 V		4.5	5	5.5	
V <sub>IH</sub>	Driver and control high-level input voltage	DIN, $\overline{\text{EN}}$ , FORCEOFF, FORCEON		V <sub>CC</sub> = 3.3 V		2	V
				V <sub>CC</sub> = 5 V		2.4	
V <sub>IL</sub>	Driver and control low-level input voltage	DIN, $\overline{\text{EN}}$ , FORCEOFF, FORCEON				0.8	V
V <sub>I</sub>	Driver and control input voltage	DIN, $\overline{\text{EN}}$ , FORCEOFF, FORCEON		0	5.5		V
	Receiver input voltage			-25	25		V
T <sub>A</sub>	Operating free-air temperature		MAX3223EC		0	70	°C
			MAX3223EI		-40	85	

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT	
I <sub>I</sub>	Input leakage current	$\overline{\text{EN}}$ , FORCEOFF, FORCEON		$\pm 0.01$	$\pm 1$	$\mu\text{A}$	
I <sub>CC</sub>	Supply current	Auto-powerdown disabled	V <sub>CC</sub> = 3.3 V or 5 V, T <sub>A</sub> = 25°C, No load, FORCEOFF and FORCEON at V <sub>CC</sub>		0.3	1	mA
		Powered off	No load, FORCEOFF at GND		1	10	$\mu\text{A}$
		Auto-powerdown enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded		1	10	

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

## DRIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND	5	5.4		V
V <sub>OL</sub>	Low-level output voltage	DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND	–5	–5.4		V
I <sub>IH</sub>	High-level input current	V <sub>I</sub> = V <sub>CC</sub>		$\pm 0.01$	$\pm 1$	$\mu$ A
I <sub>IL</sub>	Low-level input current	V <sub>I</sub> at GND		$\pm 0.01$	$\pm 1$	$\mu$ A
I <sub>OS</sub>	Short-circuit output current <sup>(3)</sup>	V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0 V		$\pm 35$	$\pm 60$	mA
		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0 V				
r <sub>o</sub>	Output resistance	V <sub>CC</sub> , V <sub>+</sub> , and V <sub>–</sub> = 0 V, V <sub>O</sub> = $\pm 2$ V	300	10M		$\Omega$
I <sub>OZ</sub>	Output leakage current	FORCEOFF = GND, V <sub>CC</sub> = 3 V to 3.6 V, V <sub>O</sub> = $\pm 12$ V			$\pm 25$	$\mu$ A
		FORCEOFF = GND, V <sub>CC</sub> = 4.5 V to 5.5 V, V <sub>O</sub> = $\pm 12$ V			$\pm 25$	

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS		MIN	TYP <sup>(2)</sup>	MAX	UNIT
	Maximum data rate	C <sub>L</sub> = 1000 pF, One DOUT switching,	R <sub>L</sub> = 3 k $\Omega$ , See Figure 1	250	500		kbit/s
t <sub>sk(p)</sub>	Pulse skew <sup>(3)</sup>	C <sub>L</sub> = 150 pF to 2500 pF, See Figure 2	R <sub>L</sub> = 3 k $\Omega$ to 7 k $\Omega$ ,		100		ns
SR(tr)	Slew rate, transition region (See Figure 1)	R <sub>L</sub> = 3 k $\Omega$ to 7 k $\Omega$ , V <sub>CC</sub> = 3.3 V	C <sub>L</sub> = 150 pF to 1000 pF	6		30	V/ $\mu$ s
			C <sub>L</sub> = 150 pF to 2500 pF	4		30	

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> – t<sub>PHL</sub>| of each channel of the same device.

# MAX3223E

## 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

### WITH $\pm 15$ -kV ESD PROTECTION

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## RECEIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
$V_{OH}$ High-level output voltage	$I_{OH} = -1$ mA	$V_{CC} - 0.6$	$V_{CC} - 0.1$		V
$V_{OL}$ Low-level output voltage	$I_{OL} = 1.6$ mA			0.4	V
$V_{IT+}$ Positive-going input threshold voltage	$V_{CC} = 3.3$ V		1.6	2.4	V
	$V_{CC} = 5$ V		1.9	2.4	
$V_{IT-}$ Negative-going input threshold voltage	$V_{CC} = 3.3$ V	0.6	1.1		V
	$V_{CC} = 5$ V	0.6	1.4		
$V_{hys}$ Input hysteresis ( $V_{IT+} - V_{IT-}$ )			0.5		V
$I_{OZ}$ Output leakage current	$\overline{EN} = V_{CC}$		$\pm 0.05$		$\mu$ A
$r_i$ Input resistance	$V_I = \pm 3$ V to $\pm 25$ V	3	5		k $\Omega$

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at  $V_{CC} = 3.3$  V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at  $V_{CC} = 5$  V  $\pm$  0.5 V.

(2) All typical values are at  $V_{CC} = 3.3$  V or  $V_{CC} = 5$  V, and  $T_A = 25^\circ$ C.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP <sup>(2)</sup>	UNIT
$t_{PLH}$ Propagation delay time, low- to high-level output	$C_L = 150$ pF, See Figure 3	150	ns
$t_{PHL}$ Propagation delay time, high- to low-level output	$C_L = 150$ pF, See Figure 3	150	ns
$t_{en}$ Output enable time	$C_L = 150$ pF, $R_L = 3$ k $\Omega$ , See Figure 4	200	ns
$t_{dis}$ Output disable time	$C_L = 150$ pF, $R_L = 3$ k $\Omega$ , See Figure 4	200	ns
$t_{sk(p)}$ Pulse skew <sup>(3)</sup>	See Figure 3	50	ns

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at  $V_{CC} = 3.3$  V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at  $V_{CC} = 5$  V  $\pm$  0.5 V.

(2) All typical values are at  $V_{CC} = 3.3$  V or  $V_{CC} = 5$  V, and  $T_A = 25^\circ$ C.

(3) Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

## AUTO-POWERDOWN SECTION

### Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$		2.7	V
$V_{T(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{INVALID}$ low-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-0.3	0.3	V
$V_{OH}$	$\overline{INVALID}$ high-level output voltage	$I_{OH} = 1\text{ mA}$ , $\overline{FORCEOFF} = V_{CC}$	FORCEON = GND,	$V_{CC} - 0.6$		V
$V_{OL}$	$\overline{INVALID}$ low-level output voltage	$I_{OL} = 1.6\text{ mA}$ , $\overline{FORCEOFF} = V_{CC}$	FORCEON = GND,		0.4	V

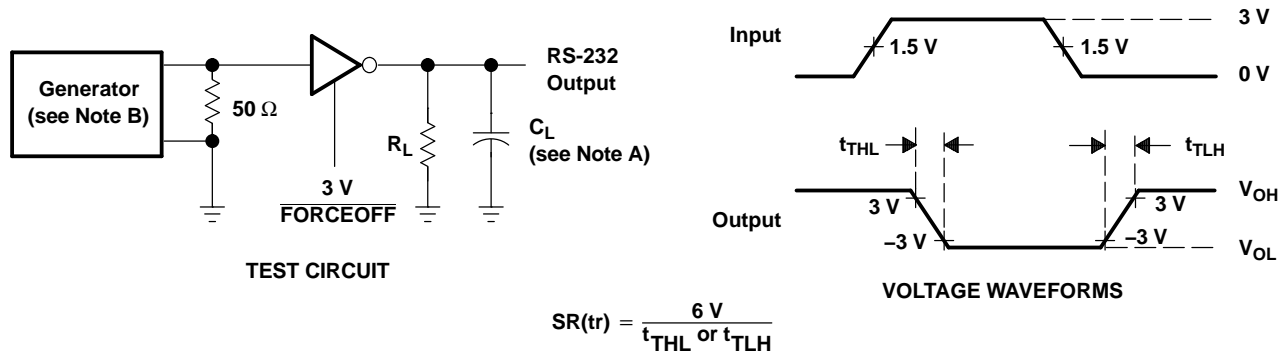
### Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TYP <sup>(1)</sup>	UNIT
$t_{valid}$	Propagation delay time, low- to high-level output	1	$\mu\text{s}$
$t_{invalid}$	Propagation delay time, high- to low-level output	30	$\mu\text{s}$
$t_{en}$	Supply enable time	100	$\mu\text{s}$

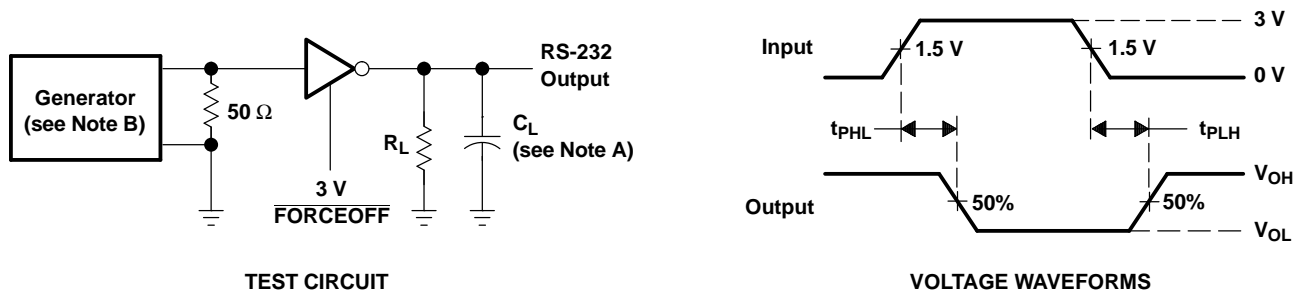
(1) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

**PARAMETER MEASUREMENT INFORMATION**



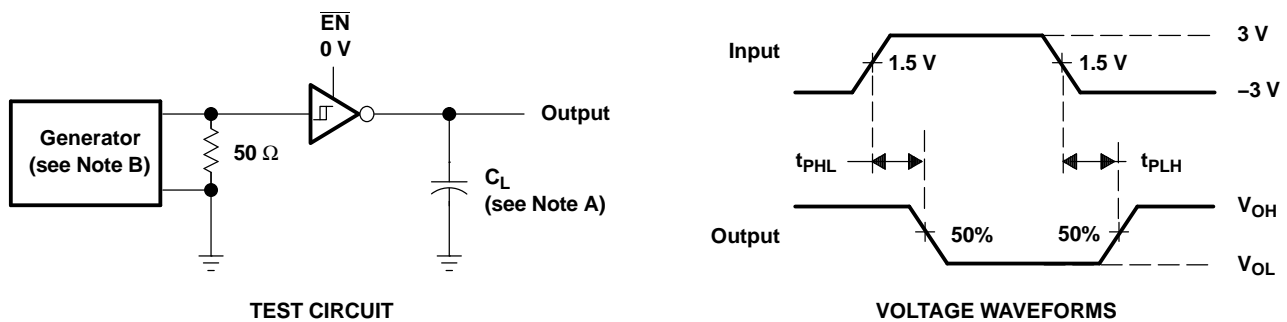
- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

**Figure 1. Driver Slew Rate**



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

**Figure 2. Driver Pulse Skew**

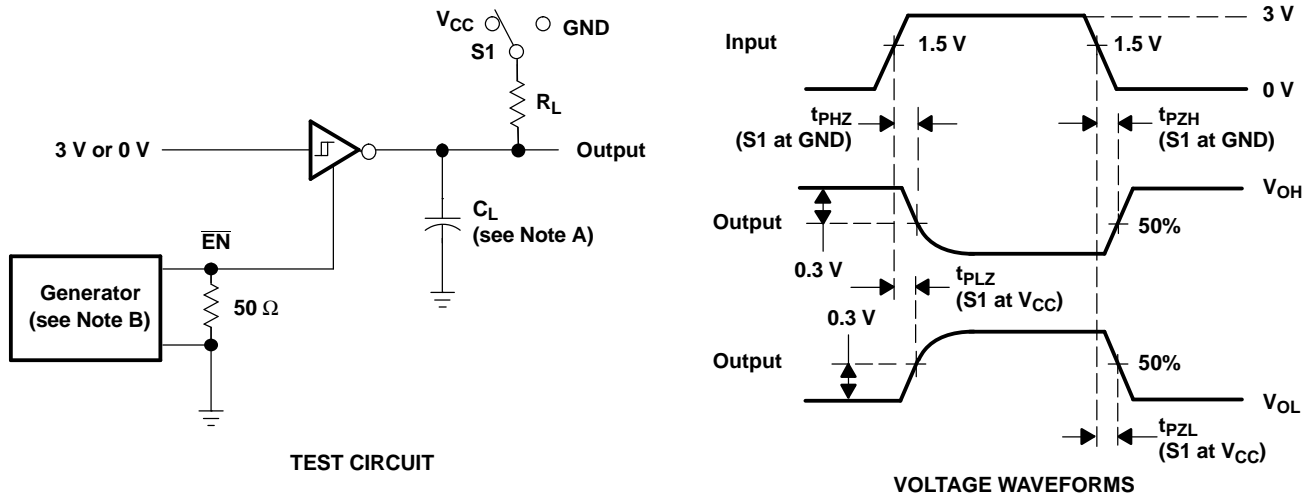


- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

**Figure 3. Receiver Propagation Delay Times**



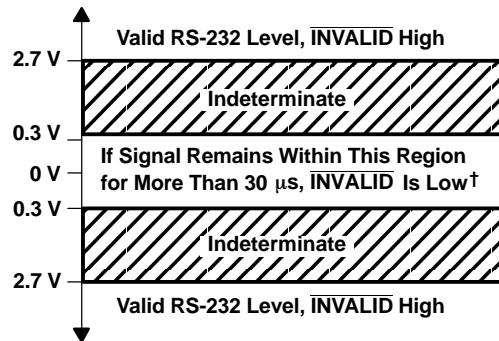
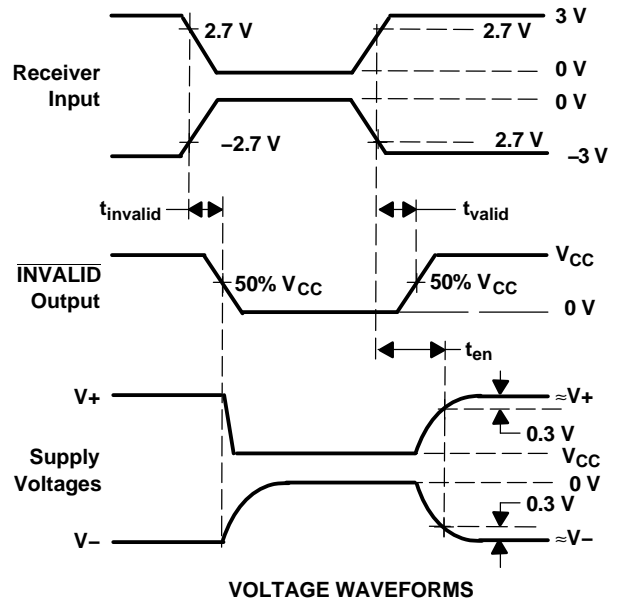
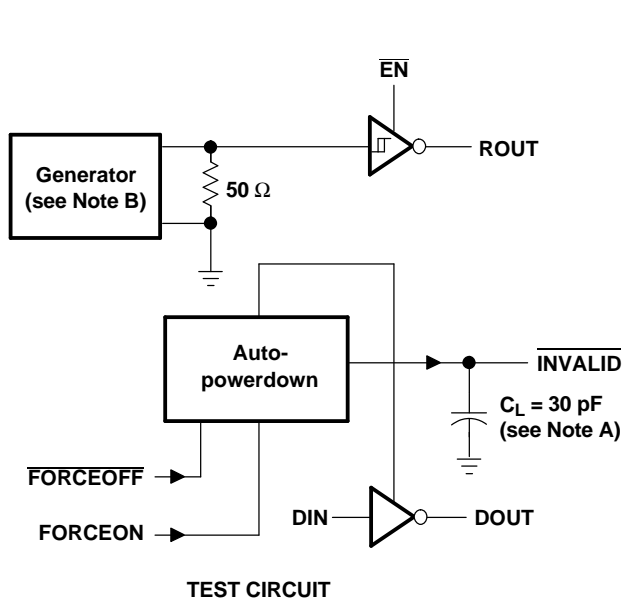
**PARAMETER MEASUREMENT INFORMATION (continued)**



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

**Figure 4. Receiver Enable and Disable Times**

PARAMETER MEASUREMENT INFORMATION (continued)

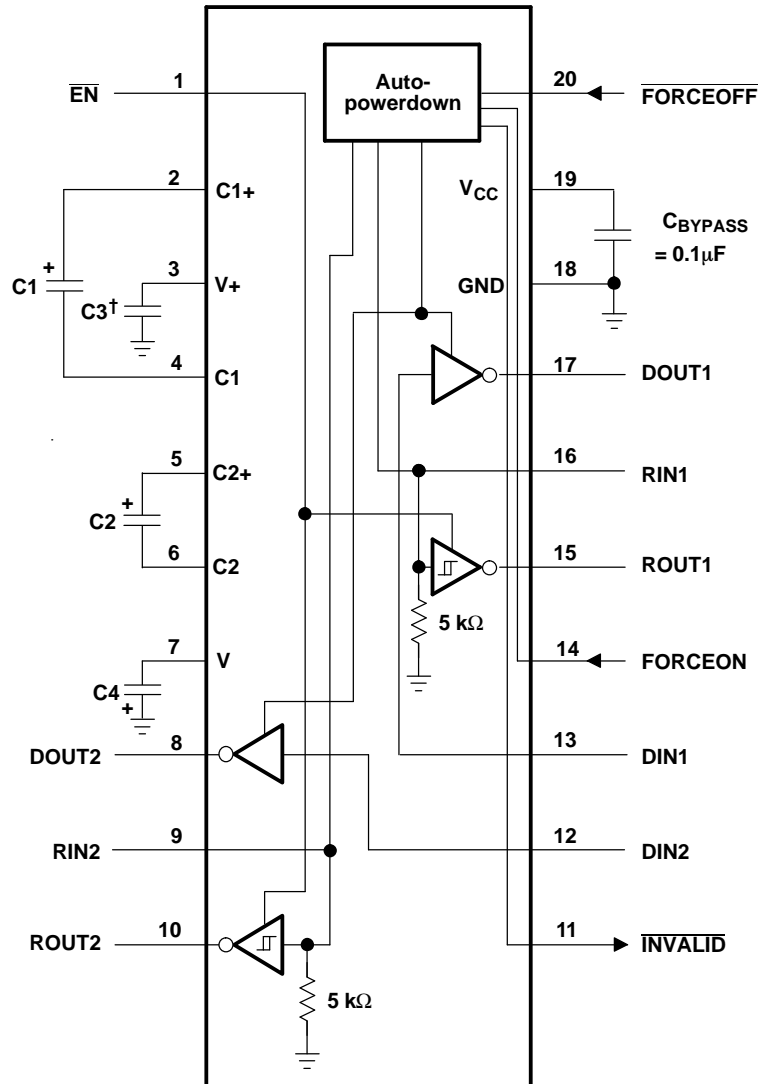


† Auto-powerdown disables drivers and reduces supply current to 1  $\mu$ A

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 5.  $\overline{\text{INVALID}}$  Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



† C3 can be connected to  $V_{CC}$  or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

$V_{CC}$  vs CAPACITOR VALUES

$V_{CC}$	C1	C2, C3, and C4
3.3 V $\pm$ 0.3 V	0.1 $\mu$ F	0.1 $\mu$ F
5 V $\pm$ 0.5 V	0.047 $\mu$ F	0.33 $\mu$ F
3 V to 5.5 V	0.1 $\mu$ F	0.47 $\mu$ F

Figure 6. Typical Operating Circuit and Capacitor Values

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
MAX3223ECDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDBG4	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223ECRHLR	PREVIEW	QFN	RHL	24	1000	TBD	Call TI	Call TI
MAX3223EIDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDBG4	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223EIPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
MAX3223EIRHLR	PREVIEW	QFN	RHL	24	1000	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3223ECDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3223ECDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
MAX3223ECPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
MAX3223EIDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3223EIDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
MAX3223EIPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3223ECDBR	SSOP	DB	20	2000	346.0	346.0	33.0
MAX3223ECDWR	SOIC	DW	20	2000	346.0	346.0	41.0
MAX3223ECPWR	TSSOP	PW	20	2000	346.0	346.0	33.0
MAX3223EIDBR	SSOP	DB	20	2000	346.0	346.0	33.0
MAX3223EIDWR	SOIC	DW	20	2000	346.0	346.0	41.0
MAX3223EIPWR	TSSOP	PW	20	2000	346.0	346.0	33.0

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153



DW (R-PDSO-G20)

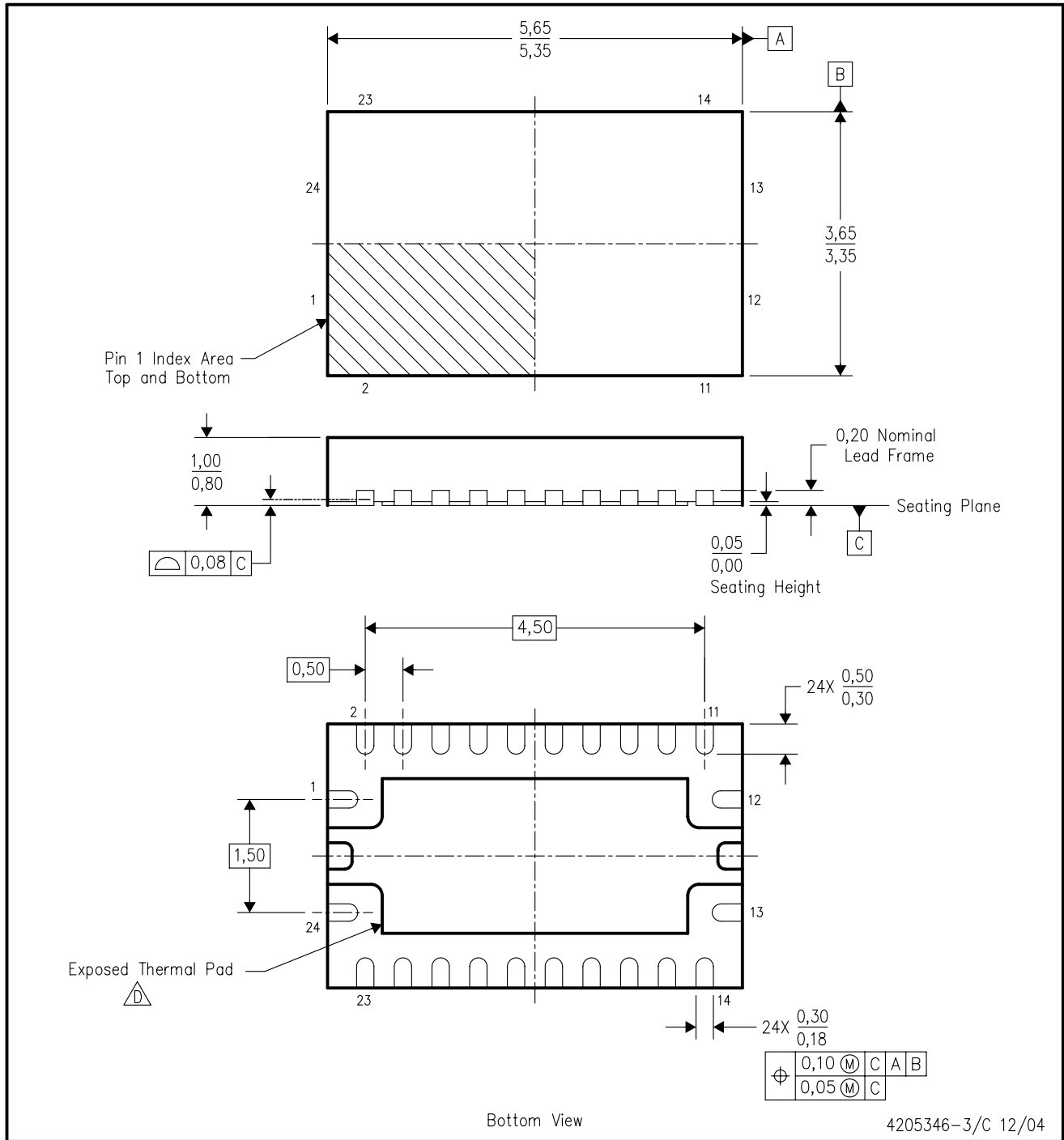
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

RHL (R-PQFP-N24)

PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - D. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - E. JEDEC MO-241 package registration pending.

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